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ЭΓ			ICA	$\mathbf{I}$	

CUSTOMER . MIE

SAMPLE CODE . SG9832LRS-AGB-H-Q

MASS PRODUCTION CODE . PG9832LRS-AGB-H-Q

SAMPLE VERSION . 01

SPECIFICATIONS EDITION . 001

DRAWING NO. (Ver.) JLMD-PG9832LRS-AGB-H-Q\_001

PACKAGING NO. (Ver.) JPKG-PG9832LRS-AGB-H-Q\_001

# **Customer Approved**

Date:

POWERTIP 2015.09.08 JS RD APPROVED

Approved	Checked	Designer
閆偉	劉進	張斌

- ☐ Preliminary specification for design input
- Specification for sample approval

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# **History of Version**

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Total: 30 Page



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Appendix: 1. LCM Drawing

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# 1. SPECIFICATIONS

## 1.1 Features

Item	Standard Value
Display Type	98*32 dots
LCD Type	STN , Gray , Transflective , Positive , Extended Temp.
Driver Condition	LCD Module : 1/32 Duty, 1/6Bias
Viewing Direction	6 O'clock
Weight	28.0 g
Interface	8 bit interface
Controller / Driver IC	SBN1661G
	THIS PRODUCT CONFORMS THE ROHS OF PTC
ROHS	Detail information please refer web side :
	http://www.powertip.com.tw/news.php?area_id_view=1085560481/

1.2 Mechanical Specifications

Item	Standard Value	Unit
Outline Dimension	52.0(L) * 44.0(w) * 13.5(H)(Max)	
Viewing Area	46.0(L) * 18.5(w)	mm
Active Area	43.08(L) * 15.64(w)	mm
Dot Size	0.40(L) * 0.45(w)	mm
Dot Pitch	0.44(L) * 0.49(w)	mm

Note: For detailed information please refer to LCM drawing

# 1.3 Absolute Maximum Ratings

Item	Symbol	Condition	Min.	Max.	Unit
Power Supply Voltage	VDD	-	-0.3	7.0	V
LCD Driver Supply voltage	VLCD	-	-	13	V
Input Voltage	V <sub>IN</sub>		-0.3	VDD+0.3	
Operating Temperature	T <sub>OP</sub>	•	-20	+70	°C
Storage Temperature	Tst		-30	+80	°C
Storage Humidity	H <sub>D</sub>	Ta < 60 °C	-	90	%RH



## 1.4 DC Electrical Characteristics

 $VDD = 5.0\pm0.5V$ , VSS = 0V,  $Ta = 25^{\circ}C$ 

Item	Symbol	Condition	Min.	Тур.	Max.	Unit
Logic Supply Voltage	VDD	-	4.5	5.0	5.5	V
"H" Input Voltage	Vıн	-	VDD-2.2		VDD	V
"L" Input Voltage	VIL	-	-	-	0.8	V
"H" Output Voltage	Vон	Iон=-3.0mA	VDD-0.3	-	VDD	V
"L" Output Voltage	Vol	IoL=3.0mA	•	-	0.3	V
Supply Current	IDD	$V_{DD}=5.0V; V_{OP}=6.5V;$	-	1.5	3.0	mA
		-20°C	1	-		
LCM Driver Voltage	Vop *1	+25°C	6.3	6.5	6.7	V
		+70°C	-	-	-	

Note: \*1. The Vop test point is VDD-V0



## 1.5 Optical Characteristics

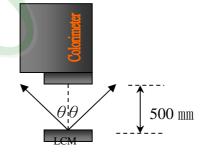
LCD Panel: 1/32Duty, 1/6Bias, VLCD = 6.36V,Ta = 25°C

Item		Symbol	Conditions	Min.	Тур.	Max.	Unit	Reference
Response Time	Rise	tr		-	150	-	ms	Note2
Response Time	Fall	tf	-	-	280	-	ms	Notez
	Top	$\theta$ +		40	-	1		
Viewing angle	Bottom	θ-	C>2.0	40		-	Deg.	Notes 1
range	Left	θL	C>2.0	45		-		Notes 1
	Right	θR		45		-		
Contrast Rat	tio	С	$\theta = 0^{\circ}$	5	7	1	-	Note 3
Average Brightness (with LCD) *2		IV	IF=120mA	10	20	-	cd/m2	Note 4
Uniformity	*1	△B		70		•	%	

#### Note 4:

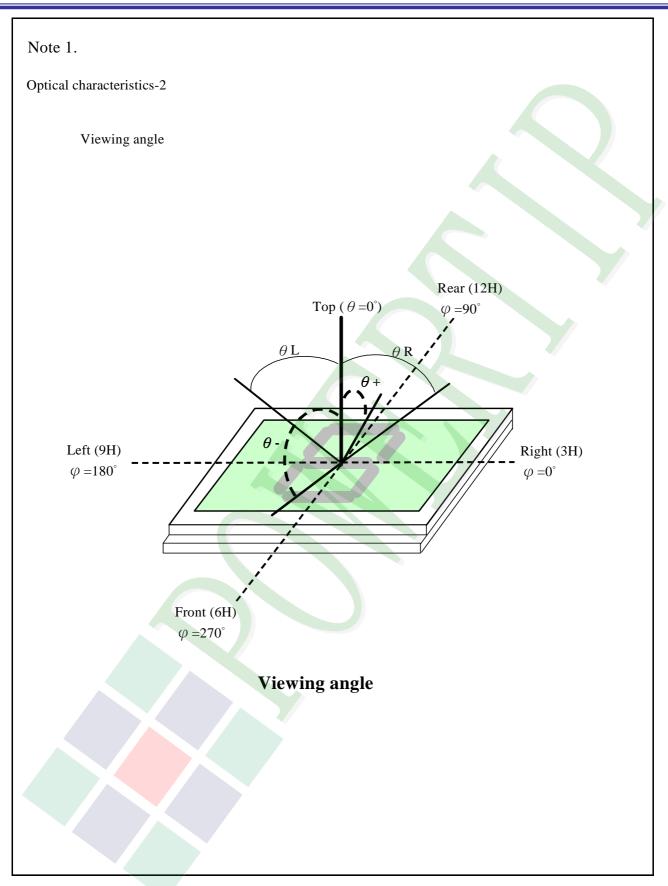
- $1 : \triangle B = B(min) / B(max) * 100\%$
- 2 : Measurement Condition for Optical Characteristics:
  - a : Environment:  $25^{\circ}\text{C} \pm 5^{\circ}\text{C}$  /  $60\pm 20\%$  R.H , no wind , dark room below 10 Lux at typical lamp current and typical operating frequency.
  - b: Measurement Distance:  $500 \pm 50 \text{ mm}$ ,  $(\theta = 0^{\circ})$
  - c : Equipment: TOPCON BM-7 fast , (field  $1^{\circ})$  , after 10 minutes operation.
  - d: The uncertainty of the C.I.E coordinate measurement  $\pm 0.01$ , Average Brightness  $\pm 4\%$



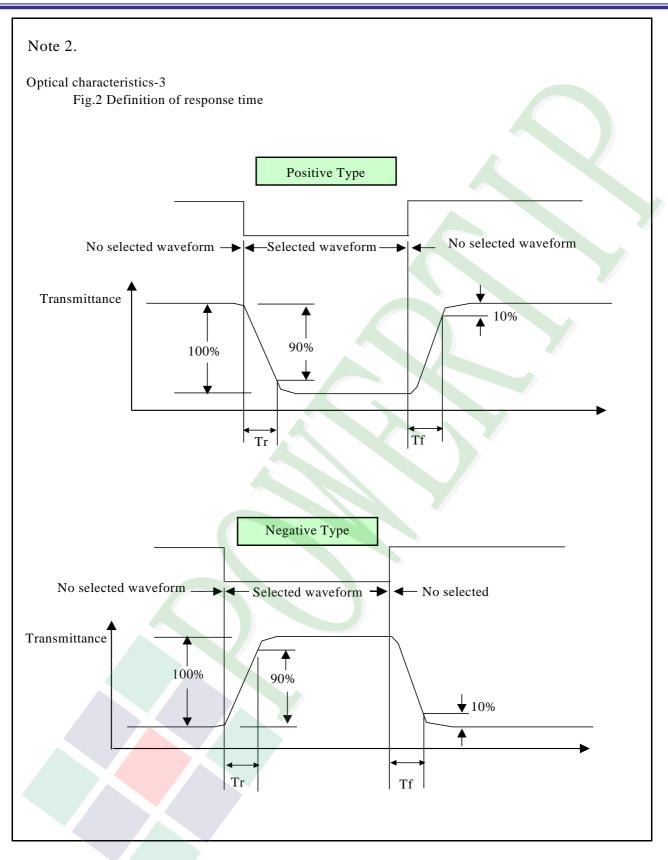


Colorimeter=BM-7 fast











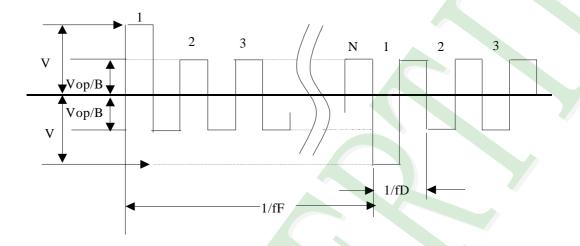
#### Electrical characteristics-2

**※**2 Drive waveform

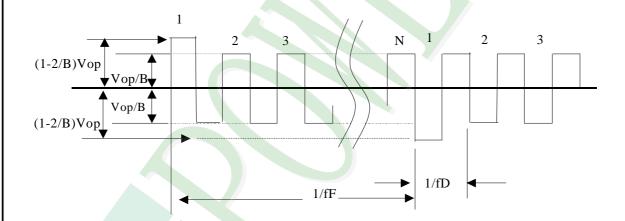
Vop: Drive voltage fF: Frame frequency 1/B: Bias fD: Drive frequency

N: Duty

#### (1) Selected waveform



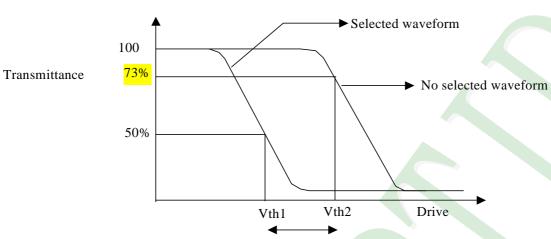
#### (2) Non-Selected wave form



Note:

Frame frequency is defined as follows: Common side supply voltage peak - to - peak /2 = 1 period

Note 3.: Definition of Vth



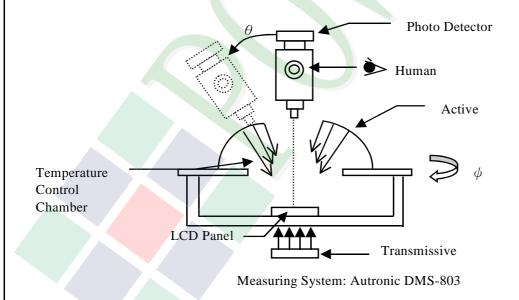
Active voltage range

	Vth1	Vth2
View direction	10°	40°
Drive waveform	(Selected waveform)	(No selected waveform)
Transmittance	50%	73%

**※**1 Contrast ratio

= (Brightness in OFF state) / (Brightness in ON state)

Outline of Electro-Optical Characteristics Measuring System





# 1.6 Backlight Characteristics

LCD Module with LED Backlight

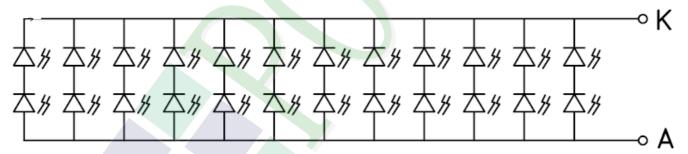
Maximum Ratings

Item	Symbol	Conditions	Min.	Max.	Unit
Forward Current	IF	Ta =25°℃	-	300	mA
Reverse Voltage	VR	Ta =25°℃	- (	10	V
Power Dissipation	PO	Ta =25°℃	-	1.38	W
Solder Temp. for 3 Second	-	-		320	$^{\circ}\!\mathbb{C}$

#### Electrical / Optical Characteristics

Item	Symbol	Conditions	Min.	Тур.	Max.	Unit
Forward Voltage	VF	IF=120mA		4.2	4.6	V
Reverse Current	IR	VR=10V	-		0.12	mA
Average Brightness (without LCD)	IV	IF=120 mA	200	250	-	cd/m <sup>2</sup>
Wavelength (without LCD)	HUE	IF=120 mA	569	-	576	nm
Color	Yellow-Green				•	

## Internal Circuit Diagram:





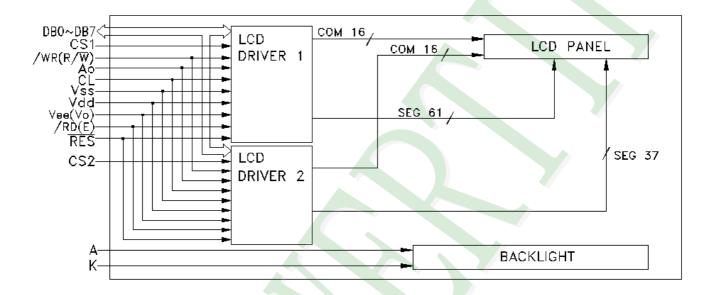
# 2. MODULE STRUCTURE

# 2.1 Counter Drawing

## 2.1.1 LCM Mechanical Diagram

\* See Appendix

## 2.1.2 Block Diagram





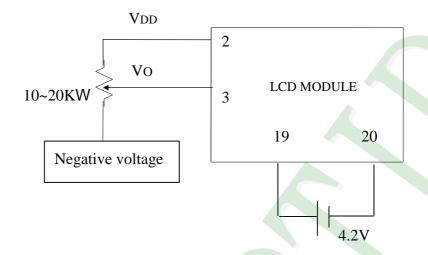


# 2.2 Interface Pin Description

Pin No.	Symbol	Function
1	VSS	Power Supply (VSS=0)
2	VDD	Power Supply (VDD>VSS)
3	VEE(VO)	Operating voltage for LCD (variable)
4	A0	"L" is instruction "H" is data
5	CS1	Chip enable active "L", segment 0~segment 61
6	CS2	Chip Enable active "L", segment 62~segment 98
7	CL	Clock input 2KHZ
8	/RD(E)	Data read (68-family MPU : Enable Signal)
9	/WR(R/W)	Data write (68-family MPU : Data read and write)
10-13	DB0~DB3	Four low order bi-directional three-state data bus lines. Used for data transfer between the MPU and the LCD module. These four are not used during 4-bit operation.
14-17	DB4~DB7	Four high order bi-directional three-state data bus lines. Used for data transfer between the MPU and the LCD module. DB7 can be used as a busy flag.
18	RES	Reset the system
19	A	Power supply for LED backlight (+)
20	K	Power supply for LED backlight (-)



# 2.2.1 Contrast Adjust

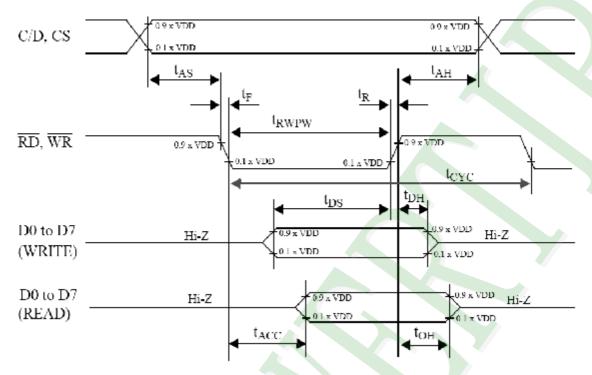






## 2.3 Timing Characteristics

#### MPU Bus Read/Write I (80-family MPU)



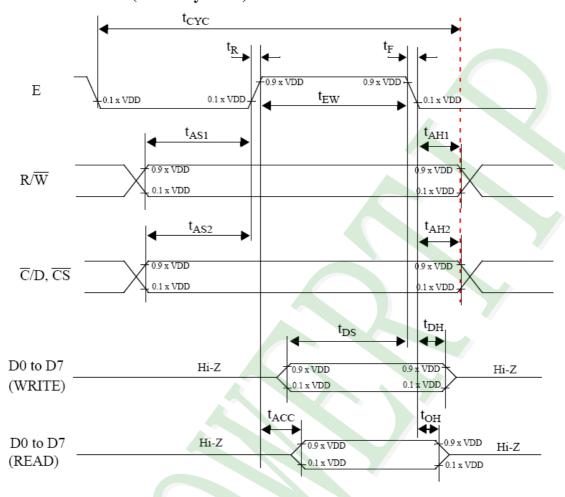
AC timing for interface with a 80-type microcontroller

 $V_{DD} = 5 \text{ V} + 10\%$ ;  $V_{SS} = 0 \text{ V}$ ;  $T_{amb} = -20 \text{ °C to } +75 \text{°C}$ .

symbol	parameter	min.	max.	test conditons	unit
$t_{AS}$	Address set-up time	20)			ns
t <sub>AH</sub>	Address hold time	10			ns
t <sub>F</sub> , t <sub>R</sub>	Read/Write pulse falling/rising time		15		ns
t <sub>rwpw</sub>	Read/Write pulse width	200			ns
t <sub>CYC</sub>	System cycle time	1000			ns
tos	Data setup time	80			ns
t <sub>DH</sub>	Data hold time	10			ns
t <sub>ACC</sub>	Data READ access time		90	CL= 100 pF.	ns
t <sub>OH</sub>	Data READ output hold time	10	60	Refer to Fig. 23.	ns



## MPU Bus Read/Write II (68-family MPU)



AC timing for interface with a 68-type microcontroller

 $V_{DD}$  = 5 V ±10%;  $V_{SS}$  = 0 V;  $T_{amb}$  = -20 °C to +75°C.

symbol	parameter	mln.	max.	test conditions	unit
t <sub>AS1</sub>	Address set-up time with respect to R/W	20			ns
t <sub>AS2</sub>	Address set-up time with respect to C/D, CS	20			ns
t <sub>ALI1</sub>	Address hold time with respect to R/W	10			ns
t <sub>ALI2</sub>	Address hold time respect with to C/D, CS	10			ns
t <sub>F</sub> , t <sub>R</sub>	Enable (E) pulse falling/rising time		15		ns
toyo	System cycle time	1000		Note 1	ns
t <sub>FWR</sub>	Enable pulse width for READ	100			ns
t <sub>FWW</sub>	Enable pulse width for WRITE	80			ns
tos	Data setup time	80			ns
t <sub>DH</sub>	Data hold time	10			ns
t <sub>ACC</sub>	Data access time		90	CL= 100 pF.	ns
tон	Data output hold time	10	60	Refer to Fig. 23.	ns

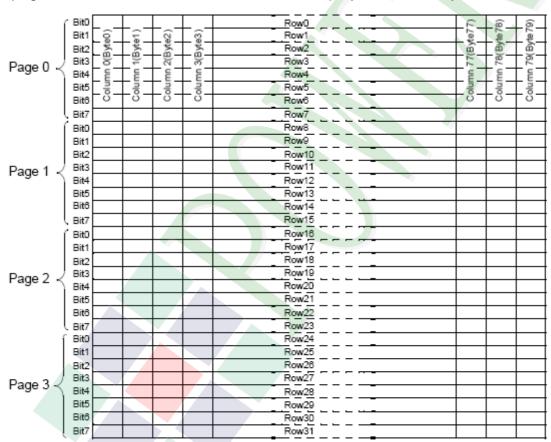


## 2.4 Display Command

COMMAND	COMMAND CODE								FUNCTION
COMMAND	D7	D6	D5	D4	D3	D2	D1	D0	FUNCTION
Write Display Data	ı	Data to be written into the Display Data Memory.				Disp	lay D	ata	Write a byte of data to the Display Data Memory.
Read Display Data		a read	from	the I	Displa	ay Da	ta		Read a byte of data from the Display Data Memory.
Read-Modify-Write	1	1	1	0	0	0	0	0	Start Read-Modify-Write operation.
END	1	1 1 1 0 1 1 1 0		0	Stop Read-Modify-Write operation.				
Software Reset	1	1	1	0	0	0	1	0	Software Reset.

#### 2.4.1 Write Display Data

The Write Display Data command writes a byte (8 bits) of data to the Display Data Memory. Data is put on the data bus by the host microcontroller. The location which accepts this byte of data is pointed to by the Page Address Register and the Column Address Register. At the end of the command operation, the content of the Column Address Register is automatically incremented by 1. For page address and column address of the Display Data Memory.



Page/Column allocation of the Display Data Memory

The setting of the control bus for issuing Write Display Data command

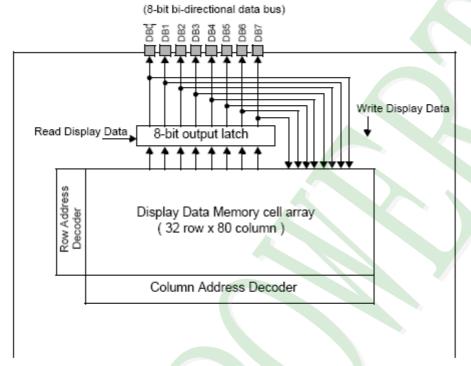
C/D	E/(RD)	R/W(WR)
1	1	0



#### 2.4.2 Read Display Data

The Read Display Data command starts a 3-step operation.

- 1. First, the current data of the internal 8-bit output latch of the Display Data Memory is read by the microcontroller, via the 8-bit data bus DB0~DB7.
- 2. Then, a byte of data of the Display Data Memory is transferred to the 8-bit output latch from a location specified by the Page Address Register and the Column Address Register,
- 3. Finally, the content of the Column Address Register is automatically incremented by one. For Display Data Write operation, a dummy write is not needed, because data can be directly written from the data bus to internal memory cells.



Read Display Data Memory

The setting of the control bus for issuing Read Display Data command

C/D	E/(RD)	R/W(WR)
1	0	1

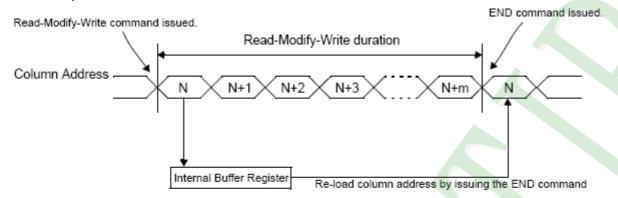
#### 2.4.3 Read-Modify-Write

When the Read-Modify-Write command is issued, the SBN1661G\_X enters into Read-Modify-Write mode.

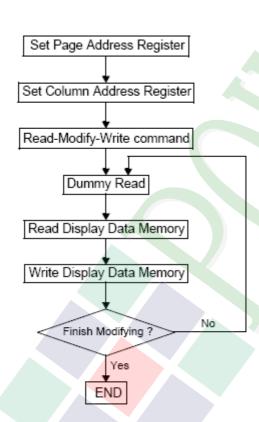
In normal operation, when a Read Display Data command or a Write Display Data command is issued, the content of the Column Address Register is automatically incremented by one after the command operation is finished. However, during Read-Modify-Write mode, the content of the Column Address Register is not incremented by one after a Read Display Data command is finished; only the Write Display Data command can make the content of the Column Address Register automatically incremented by one after the command operation is finished.



During Read-Modify-Write mode, any other registers, except the Column Address Register, can be modified. This command is useful when a block of the Display Data Memory needs to be repeatedly read and updated.



Column address change during Read-Modify-Write



The flowchart for Read-Modify-Write

The setting of the control bus for the Read-Modify-Write command

4	C/D	E/(RD)	R/W(WR)
	0	1	0

The setting of the data bus for the Read-Modify-Write command



D7(MSB)	D6	D5	D4	D3	D2	D1	D0(LSB)
1	1	1	0	0	0	0	0

The command code is E0 Hex.

#### 2.4.4 The END command

The END command releases the Read-Modify-Write mode and re-loads the Column Address Register with the value previously stored in the internal buffer (refer to Fig. 17) when the Read-Modify-Write command was issued.

The setting of the control bus for the END command

C/D	E/(RD)	R/W(WR)
0	1	0

The setting of the data bus for the END command

1 11/4	(MSB)	D6	D5	D4	D3	D2	D1	D0(LSB)
	1	1	1	0	1	1	1	0

The command code is EE Hex.

#### 2.4.5 Software RESET command

The Software Reset command is different from the hardware reset and can not be used to replace hardware reset.

When Software Reset is issued by the host microcontroller,

- the content of the Display Start Line Register is cleared to zero(A4~A0=00000),
- the Page Address Register is set to 3 (A1 A0 = 11),
- the content of the Display Data Memory remains unchanged, and
- the content of all other registers remains unchanged.

The setting of the control bus for Software RESET

C/D	E/(RD)	R/W(WR)
0	1	0

The setting of the data bus for Software RESET

D7(MSB)	D6	D5	D4	D3	D2	D1	D0(LSB)
1	1	1	0	0	0	1	0

The command code is E2 Hex.

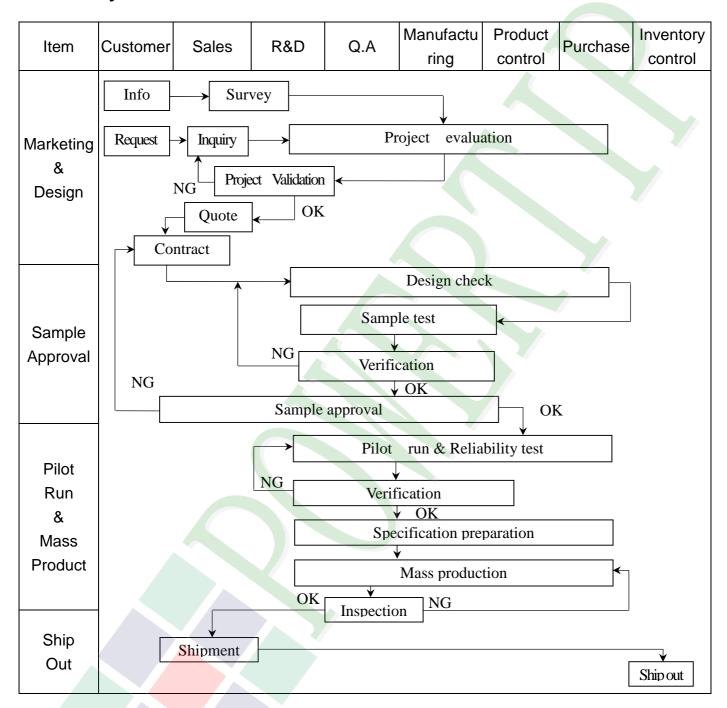
#### 2.5 JUMPER

Short: J1/J3 Other: Open

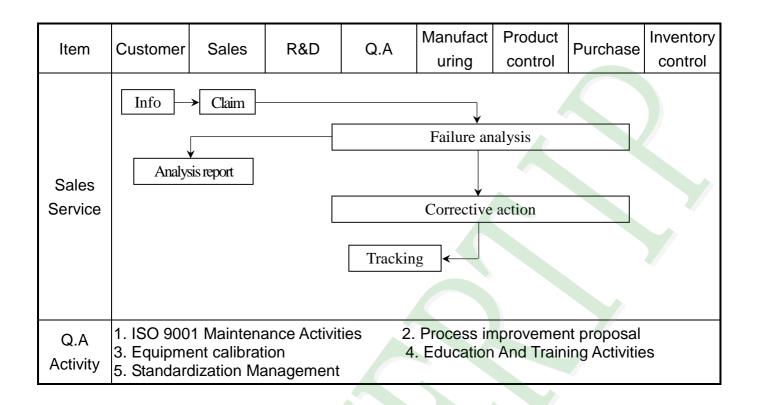


## 3. QUALITY ASSURANCE SYSTEM

# 3.1 Quality Assurance Flow Chart









## 3.2 Inspection Specification

- ◆Scope: The document shall be applied to LCD Module for Monotype and Color STN(Ver. B01).
- ♦Inspection Standard: MIL-STD-105E Table Normal Inspection Single Sampling Level Ⅱ.
- ◆Equipment : Gauge · MIL-STD · Powertip Tester · Sample
- ◆Defect Level: Major Defect AQL: 0.4; Minor Defect: AQL: 1.5.
- **♦**OUT Going Defect Level : Sampling .
- ◆Manner of appearance test :
  - (1). The test be under 20W×2 fluorescent light 'and distance of view must be at 30 cm.
  - (2). Standard of inspection: (Unit: mm)
  - (3). The test direction is base on about around 45° of vertical line. (Fig. 1)
  - (4). Definition of area . (Fig. 2)

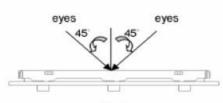


Fig.1

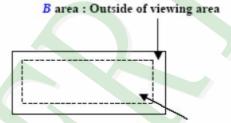


Fig. 2 A area: viewing area

## **♦** Specification:

NO	Item	Criterion	Level
		1. 1 The part number is inconsistent with work order of Production.	Major
01	Product condition	1. 2 Mixed production types.	Major
		1. 3 Assembled in inverse direction.	Major
02	Quantity	2. 1 The quantity is inconsistent with work order of production.	Major
03	Outline dimension	3. 1 Product dimension and structure must conform to Structure diagram.	Major
		4. 1 Missing line character and icon.	Major
		4. 2 No function or no display.	Major
04	Electrical Testing	4, 3 Output data is error.	Major
		4, 4 LCD viewing angle defect.	Major
		4. 5 Current consumption exceeds product specifications.	Major



NO	Item	Criterion 1				Level	
	Black or white dot \ scratch \ contamination	<ul> <li>5. 1 Round type:</li> <li>5. 1. 1 display only:</li> <li>• White and black spots on display ≤ 0. 30 mm, no more than 4 white or black spots present.</li> <li>• Densely spaced: NO more than two spots or lines within 3 mm.</li> </ul>					
	Round type	5. 1. 2 Non-display :  Dimension (diameter : Φ)		Acceptance A area	(Q'ty) B area		
0.5	$+$ $\times$ $+$ $\times$ $\times$	$\Phi \le 0.10$ $0.10 < \Phi \le 0.20$		ept no dense		>	
05	$\Phi = (x+y)/2$	$0.20 < \Phi \le 0.30$ Total quantity		2 4	Ignore		Minor
		5. 1. 3 Line type:  Dimension Acceptance (Q'ty)					
	Line type	Length (L) Width (W		A area	B as		
	<b>₹</b> W	W ≦		Accept no den	ıse		
	→ L + "	$L \le 3.0$ $0.03 < W \le $ $L \le 2.5$ $0.05 < W \le 0$		4	Igı	iore	
	1	W >(	. 075	As 1	ound type		
		Dimension (diameter : Φ)		Acceptanc	1 2		
		$\Phi \leq 0.20$	_	A area	В	area	
06	Polarizer	$0.20 < \Phi \leq 0.50$	A	3	$\dashv$		
00	Bubble	$0.50 < \Phi \le 1.00$		2	Igno	re	Minor
		$\Phi > 1.00$		0			
		Total quantity		4			



NO	Item	Criterion		
		Z: The thickness of crack W:	The width of crack. terminal length LCD side length	
		7.1 General glass chip: 7.1.1 Chip on panel surface and crack	between panels:	
		Z Z	Z Y X	
07	The crack of glass	SP Y (OK)	[NG]	Minor
		Seal width Z	Y	
		X Y	z	
		≦ a Crack can't enter viewing area	≦1/2 t	
4		≤ a Crack can't exceed the half of SP width.	1/2 t < Z ≤2 t	



NO	Item	Criterion					
		Symbols:  X: The length of crack Z: The thickness of crack t: The thickness of glass  7. 1. 2 Corner crack:					
		X Y Z					
		≤1/5 a Crack can't enter viewing area Z ≤ 1/2 t					
07	The crack of	≤1/5  a Crack can't exceed the half of SP width. $1/2$ t < Z $≤ 2$ t	Minor				
01	glass	7.2 Protrusion over terminal:	Minor				
		7. 2. 1 Chip on electrode pad:  X  X  X  X  X  Z  X  X  X  X  X  X  X					
		Front $\leq$ a $\leq$ 1/2 W $\leq$ t					
	Back Neglect						



Item	Criterion		
	Symbols:  X: The length of crack Z: The thickness of crack t: The thickness of glass  Y: The width of crack. W: terminal length a: LCD side length		
,	7.2.2 Non-conductive portion:		
The crack of glass	X Y Z	Minor	
	⊙ If the chipped area touches the ITO terminal, over 2/3 of the ITO must remain and be inspected according to electrode terminal specifications.		
	X Y Z		
	The crack of	Symbols:  X: The length of crack Z: The thickness of crack t: The thickness of glass  7. 2. 2 Non-conductive portion:  X Y: The width of crack. W: terminal length a: LCD side length  7. 2. 2 Non-conductive portion:  X Y Z    X Y Z   Side selected according to electrode terminal specifications.  7. 2. 3 Glass remain:	



NO	Item	Criterion	Level
08	Backlight elements	8. 1 Backlight can't work normally.	Major
		8. 2 Backlight doesn't light or color is wrong.	Major
		8. 3 Illumination source flickers when lit.	Major
	General appearance 9. 3	9. 1 Pin type must match type in specification sheet.	Major
		9. 2 No short circuits in components on PCB or FPC.	Major
09		9. 3 Product packaging must the same as specified on packaging specification sheet.	Minor
		9. 4 The folding and peeled off in polarizer are not acceptable.	Minor
		9. 5 The PCB or FPC between B/L assembled distance (PCB or FPC) is ≤1. 5 mm.	Minor



# 4. RELIABILITY TEST

## 4.1 Reliability Test Condition

<u> </u>	(Ver. Bol)				
NO.	TEST ITEM	TEST CONDITION			
1	High Temperature Storage Test	Keep in +80 ±2°C 96 hrs Surrounding temperature, then storage at normal condition 4hrs.			
2	Low Temperature Storage Test	Keep in -30 ±2°C 96 hrs Surrounding temperature, then storage at normal condition 4hrs.			
3	High Temperature / High Humidity Storage Test	Keep in +60 °C /90% R.H duration for 96 hrs Surrounding temperature, then storage at normal condition 4hrs. (Excluding the polarizer)			
4	Temperature Cycling Storage Test	$-30^{\circ}\mathbb{C} \rightarrow +25^{\circ}\mathbb{C} \rightarrow +80^{\circ}\mathbb{C} \rightarrow +25^{\circ}\mathbb{C}$ (30mins) (5mins) (30mins) (5mins)			
5	ESD Test	Air Discharge: Apply 2 KV with 5 times Discharge for each polarity +/-  1. Temperature ambiance: 15°C ~35°C 2. Humidity relative: 30% ~60% 3. Energy Storage Capacitance(Cs+Cd): 150pF±10% 4. Discharge Resistance(Rd): 330 Ω±10% 5. Discharge, mode of operation: Single Discharge (time between successive discharges at least 1 sec) (Tolerance if the output voltage indication: ±5%)			
6	Vibration Test (Packaged)	<ol> <li>Sine wave 10~55 Hz frequency (1 min/sweep)</li> <li>The amplitude of vibration :1.5 mm</li> <li>Each direction (X \ Y \ Z) duration for 2 Hrs</li> </ol>			
7	Drop Test (Packaged)	Packing Weight (Kg) Drop Height (cm)  0 ~ 45.4 122  45.4 ~ 90.8 76  90.8 ~ 454 61  Over 454 46			
		Drop Direction: **1 corner / 3 edges / 6 sides each 1time			



# 5. PRECAUTION RELATING PRODUCT HANDLING 5.1 SAFETY

- 5.1.1 If the LCD panel breaks, be careful not to get the liquid crystal to touch your skin.
- 5.1.2 If the liquid crystal touches your skin or clothes, please wash it off immediately by using soap and water.

#### 5.2 HANDLING

- 5.2.1 Avoid any strong mechanical shock which can break the glass.
- 5.2.2 Avoid static electricity which can damage the CMOS LSI—When working with the module, be sure to ground your body and any electrical equipment you may be using.
- 5.2.3 Do not remove the panel or frame from the module.
- 5.2.4 The polarizing plate of the display is very fragile. So , please handle it very carefully, do not touch , push or rub the exposed polarizing with anything harder than an HB pencil lead (glass , tweezers , etc.)
- 5.2.5 Do not wipe the polarizing plate with a dry cloth, as it may easily scratch the surface of plate.
- 5.2.6 Do not touch the display area with bare hands, this will stain the display area.
- 5.2.7 Do not use ketonics solvent & aromatic solvent. Use with a soft cloth soaked with a cleaning naphtha solvent.
- 5.2.8 To control temperature and time of soldering is  $320 \pm 10^{\circ}$ C and 3-5 sec.
- 5.2.9 To avoid liquid (include organic solvent) stained on LCM

#### **5.3 STORAGE**

- 5.3.1 Store the panel or module in a dark place where the temperature is 25°C ± 5°C and the humidity is below 65% RH.
- 5.3.2 Do not place the module near organics solvents or corrosive gases.
- 5.3.3 Do not crush, shake, or jolt the module.

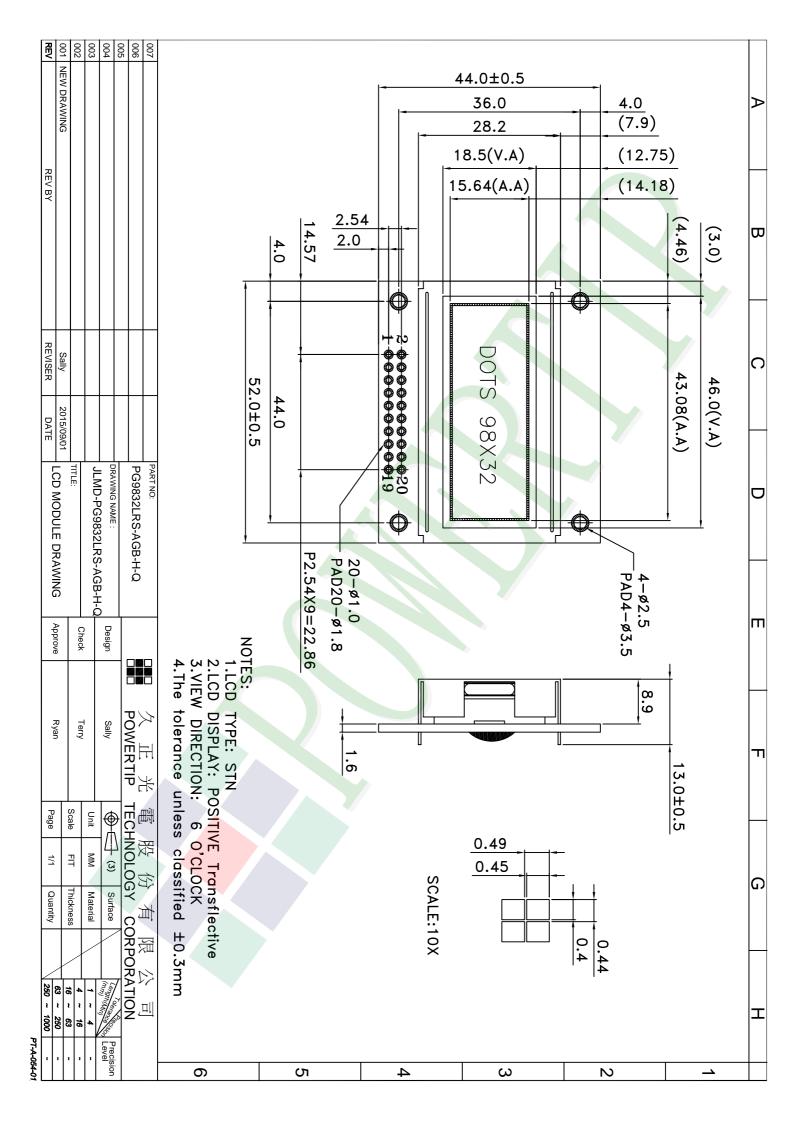
#### 5.4 TERMS OF WARRANTY

5.4.1 Applicable warrant period

The period is within thirteen months since the date of shipping out under normal using and storage conditions.

5.4.2 Unaccepted responsibility

This product has been manufactured to your company's specification as a part for use in your company's general electronic products. It is guaranteed to perform according to delivery specifications. For any other use apart from general electronic equipment, we cannot take responsibility if the product is used in nuclear power control equipment, aerospace equipment, fire and security systems or any other applications in which there is a direct risk to human life and where extremely high levels of reliability are required.



Ver.001

|Documents NO. |JPKG-PG9832LRS-AGB-H-Q|

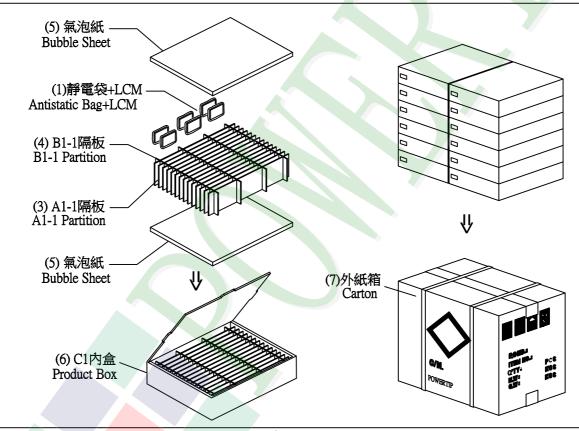
# LCM包裝規格書 LCM Packaging Specifications

Approve	Check	Contact		
Ryan	Terry	Sally		

#### 1.包裝材料規格表 (Packaging Material): (per carton)

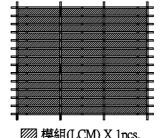
No.	Item	Model	Dimensions (mm)	1Pcs Weight	Quantity	Total Weight
1	成品 (LCM)	PG9832LRS-AGB-H-Q	52.0 X 44.0 X 13.0	0.028	468	13.104
2	靜電袋(1)Antistatic Bag	BAG100100ARABA	100 X 100	0.0011	468	0.5148
3	A1-1隔板(3)A1-1 Partition	BX29500047BZBA	295 X 47 X 3	0.0078	168	1.3104
4	B1-1隔板(4)B1-1 Partition	BX24500047BZBA	245 X 47 X 3	0.0065	48	0.312
5	氣泡紙(5)Bubble Sheet	BAG280240BWABA	280 X 240	0.006	24	0.144
6	C1内盒(6)Product Box	BX31025555AABA	310 X 255 X 55	0.13	12	1.56
7	外紙箱(7)Carton	BX52732536CCBA	527 X 325 X 360	0.83	1	0.83
8						
9						

- 2. 整箱總重量 (Total LCD Weight in carton ): 17.78 Kg±10%
- 3.單箱數量規格表 (Packaging Specifications and Quantity):
  - (1)Quantity Of Spacer: A1-1隔板 X 14, B1-1隔板 X
- (2) Total LCM quantity in carton: quantity per box 468 12 x no of boxes



#### 特 記 事 項 (REMARK)

- 4. Label Specifications: 依廠內標準作業
- 5. LCM排放示意圖(前後間隔不放置):
- 5. LCM placed as figure showing: (First and last slot should be empty)



Ø 模組(LCM) X 1pcs.